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**PART NUMBER****CLC409AB2A-ROCV**

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**Rochester Electronics****Manufactured Components**

Rochester branded components are manufactured using either die/wafers purchased from the original suppliers or Rochester wafers recreated from the original IP. All re-creations are done with the approval of the Original Component Manufacturer. (OCM)

Parts are tested using original factory test programs or Rochester developed test solutions to guarantee product meets or exceeds the OCM data sheet.

**Quality Overview**

- ISO-9001
- AS9120 certification
- Qualified Manufacturers List (QML) MIL-PRF-38535
  - Class Q Military
  - Class V Space Level

**Qualified Suppliers List of Distributors (QSLD)**

- Rochester is a critical supplier to DLA and meets all industry and DLA standards.

Rochester Electronics, LLC is committed to supplying products that satisfy customer expectations for quality and are equal to those originally supplied by industry manufacturers.

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*The original manufacturer's datasheet accompanying this document reflects the performance and specifications of the Rochester manufactured version of this device. Rochester Electronics guarantees the performance of its semiconductor products to the original OCM specifications. 'Typical' values are for reference purposes only. Certain minimum or maximum ratings may be based on product characterization, design, simulation, or sample testing.*

REVISIONS

LTR	DESCRIPTION	DATE (YR-MO-DA)	APPROVED
A	Make changes to case outline 2 pin assignments; for pin 2, delete "NC" and substitute "V <sub>NONIN</sub> "; for pin 4 delete "NC" and substitute "-V <sub>CC</sub> "; for pin 6, delete "V <sub>INV</sub> " and substitute "NC"; for pin 8, delete "V <sub>NONINV</sub> " and substitute "NC"; for pin 9, delete "-V <sub>CC</sub> " and substitute "NC"; pin 12, delete "NC" and substitute "V <sub>OUT</sub> "; for pin 14, delete "V <sub>OUT</sub> " and substitute "+V <sub>CC</sub> "; for pin 16, delete "+V <sub>CC</sub> " and substitute "NC"; for pin 20, delete "NC" and substitute "V <sub>INV</sub> ". Changes in accordance with N.O.R. 5962-R140-94.	94-03-30	M. A. FRYE
B	Table I; Common mode rejection ratio, CMRR, test: In symbol column, delete "4" and substitute "3". Changes in accordance with N.O.R. 5962-R011-95.	94-10-14	M. A. FRYE
C	Table I. 2nd harmonic distortion test. With a condition of "2 VPP at 20 MHz", for a group A subgroup 5, delete the max limit of "-60 dBc" and substitute "-57 dBc". Changes in accordance with N.O.R. 5962-R202-97.	97-02-07	R. MONNIN
D	Make change to second harmonic distortion test as specified in TABLE I. Redrawn. - ro	97-12-11	R. MONNIN
E	Make changes to theta JC and theta JA as specified under 1.3. Make changes +VO, -VO, GFPL, GFPH, GFR1, GFR2, HD2, and HD3 tests as specified under table I. - ro	99-02-26	R. MONNIN
F	Replaced reference to MIL-STD-973 with reference to MIL-PRF-38535. - ro	05-04-01	R. MONNIN
G	Update document paragraphs to current MIL-PRF-38535 requirements. - ro	13-08-07	C. SAFFLE
H	Drawing updated to reflect current MIL-PRF-38535 requirements. -rrp	18-09-25	C. SAFFLE



REV																		
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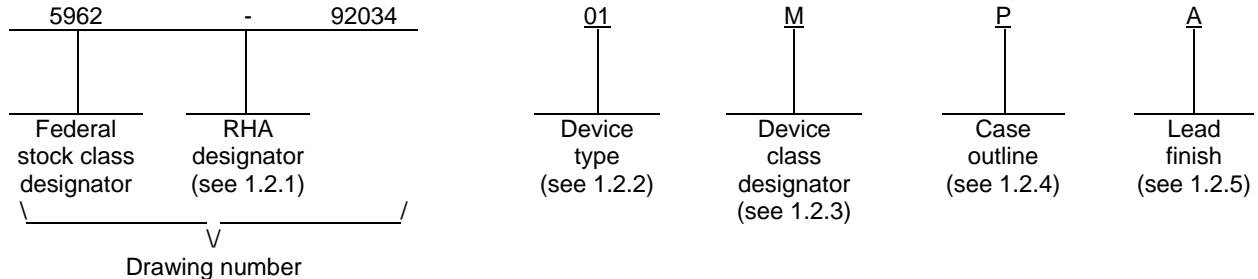
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PMIC N/A	PREPARED BY DAN WONNELL	<b>DLA LAND AND MARITIME</b> <b>COLUMBUS, OHIO 43218-3990</b> <a href="http://www.dla.mil/landandmaritime">http://www.dla.mil/landandmaritime</a>												
<b>STANDARD MICROCIRCUIT DRAWING</b>  THIS DRAWING IS AVAILABLE FOR USE BY ALL DEPARTMENTS AND AGENCIES OF THE DEPARTMENT OF DEFENSE  AMSC N/A	CHECKED BY CHARLES E. BESORE													
	APPROVED BY MICHAEL A. FRYE	MICROCIRCUIT, LINEAR, OPERATIONAL AMPLIFIER, WIDEBAND, LOW DISTORTION, MONOLITHIC SILICON												
	DRAWING APPROVAL DATE 93-02-01													
	REVISION LEVEL H		<table border="1"> <tr> <td>SIZE</td> <td>CAGE CODE</td> <td rowspan="2"><b>5962-92034</b></td> </tr> <tr> <td>A</td> <td><b>67268</b></td> </tr> </table>	SIZE	CAGE CODE	<b>5962-92034</b>	A	<b>67268</b>						
SIZE	CAGE CODE	<b>5962-92034</b>												
A	<b>67268</b>													
		SHEET	1 OF 11											

1. SCOPE

1.1 Scope. This drawing documents two product assurance class levels consisting of high reliability (device class Q and M) and space application (device class V). A choice of case outlines and lead finishes are available and are reflected in the Part or Identifying Number (PIN). When available, a choice of Radiation Hardness Assurance (RHA) levels is reflected in the PIN.

1.2 PIN. The PIN is as shown in the following example:



1.2.1 RHA designator. Device classes Q and V RHA marked devices meet the MIL-PRF-38535 specified RHA levels and are marked with the appropriate RHA designator. Device class M RHA marked devices meet the MIL-PRF-38535, appendix A specified RHA levels and are marked with the appropriate RHA designator. A dash (-) indicates a non-RHA device.

1.2.2 Device type(s). The device type(s) identify the circuit function as follows:

<u>Device type</u>	<u>Generic number</u>	<u>Circuit function</u>
01	CLC409	Operational amplifier, wideband, low distortion

1.2.3 Device class designator. The device class designator is a single letter identifying the product assurance level as follows:

<u>Device class</u>	<u>Device requirements documentation</u>
M	Vendor self-certification to the requirements for MIL-STD-883 compliant, non-JAN class level B microcircuits in accordance with MIL-PRF-38535, appendix A
Q or V	Certification and qualification to MIL-PRF-38535

1.2.4 Case outline(s). The case outline(s) are as designated in MIL-STD-1835 and as follows:

<u>Outline letter</u>	<u>Descriptive designator</u>	<u>Terminals</u>	<u>Package style</u>
P	GDIP1-T8 or CDIP2-T8	8	Dual-in-line
2	CQCC1-N20	20	Square leadless chip carrier

1.2.5 Lead finish. The lead finish is as specified in MIL-PRF-38535 for device classes Q and V or MIL-PRF-38535, appendix A for device class M.

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1.3 Absolute maximum ratings. 1/

Supply voltage (VCC) .....	±7 V dc
Common mode input voltage (VCM) .....	±VCC
Differential input voltage .....	+10 V dc
Output current (IO) .....	±70 mA
Power dissipation (PD) .....	1.2 W
Junction temperature (TJ) .....	175°C
Lead temperature (soldering, 10 seconds) .....	+300°C
Storage temperature range .....	-65°C to +125°C
Thermal resistance, junction to ambient (θJA):	
Case P .....	132°C/W
	77°C/W at 500 linear feet per minute (LFPM)
Case 2 .....	97°C/W
	67°C/W at 500 linear feet per minute (LFPM)
Thermal resistance, junction to case (θJC):	
Case P .....	26°C/W
Case 2 .....	27°C/W

1.4 Recommended operating conditions.

Supply voltage (VCC) .....	±5 V dc
Gain range .....	±1 to ±10
Ambient operating temperature range (TA) .....	-55°C to +125°C

2. APPLICABLE DOCUMENTS

2.1 Government specification, standards, and handbooks. The following specification, standards, and handbooks form a part of this drawing to the extent specified herein. Unless otherwise specified, the issues of these documents are those cited in the solicitation or contract.

DEPARTMENT OF DEFENSE SPECIFICATION

MIL-PRF-38535 - Integrated Circuits, Manufacturing, General Specification for.

DEPARTMENT OF DEFENSE STANDARDS

MIL-STD-883 - Test Method Standard Microcircuits.  
MIL-STD-1835 - Interface Standard Electronic Component Case Outlines.

DEPARTMENT OF DEFENSE HANDBOOKS

MIL-HDBK-103 - List of Standard Microcircuit Drawings.  
MIL-HDBK-780 - Standard Microcircuit Drawings.

(Copies of these documents are available online at <http://quicksearch.dla.mil/>.)

2.2 Order of precedence. In the event of a conflict between the text of this drawing and the references cited herein, the text of this drawing takes precedence. Nothing in this document, however, supersedes applicable laws and regulations unless a specific exemption has been obtained.

1/ Stresses above the absolute maximum rating may cause permanent damage to the device. Extended operation at the maximum levels may degrade performance and affect reliability.

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### 3. REQUIREMENTS

3.1 Item requirements. The individual item requirements for device classes Q and V shall be in accordance with MIL-PRF-38535 as specified herein, or as modified in the device manufacturer's Quality Management (QM) plan. The modification in the QM plan shall not affect the form, fit, or function as described herein. The individual item requirements for device class M shall be in accordance with MIL-PRF-38535, appendix A for non-JAN class level B devices and as specified herein.

3.2 Design, construction, and physical dimensions. The design, construction, and physical dimensions shall be as specified in MIL-PRF-38535 and herein for device classes Q and V or MIL-PRF-38535, appendix A and herein for device class M.

3.2.1 Case outlines. The case outlines shall be in accordance with 1.2.4 herein.

3.2.2 Terminal connections. The terminal connections shall be as specified on figure 1.

3.3 Electrical performance characteristics and postirradiation parameter limits. Unless otherwise specified herein, the electrical performance characteristics and postirradiation parameter limits are as specified in table I and shall apply over the full ambient operating temperature range.

3.4 Electrical test requirements. The electrical test requirements shall be the subgroups specified in table II. The electrical tests for each subgroup are defined in table I.

3.5 Marking. The part shall be marked with the PIN listed in 1.2 herein. In addition, the manufacturer's PIN may also be marked. For packages where marking of the entire SMD PIN number is not feasible due to space limitations, the manufacturer has the option of not marking the "5962-" on the device. For RHA product using this option, the RHA designator shall still be marked. Marking for device classes Q and V shall be in accordance with MIL-PRF-38535. Marking for device class M shall be in accordance with MIL-PRF-38535, appendix A.

3.5.1 Certification/compliance mark. The certification mark for device classes Q and V shall be a "QML" or "Q" as required in MIL-PRF-38535. The compliance mark for device class M shall be a "C" as required in MIL-PRF-38535, appendix A.

3.6 Certificate of compliance. For device classes Q and V, a certificate of compliance shall be required from a QML-38535 listed manufacturer in order to supply to the requirements of this drawing (see 6.6.1 herein). For device class M, a certificate of compliance shall be required from a manufacturer in order to be listed as an approved source of supply in MIL-HDBK-103 (see 6.6.2 herein). The certificate of compliance submitted to DLA Land and Maritime-VA prior to listing as an approved source of supply for this drawing shall affirm that the manufacturer's product meets, for device classes Q and V, the requirements of MIL-PRF-38535 and herein or for device class M, the requirements of MIL-PRF-38535, appendix A and herein.

3.7 Certificate of conformance. A certificate of conformance as required for device classes Q and V in MIL-PRF-38535 or for device class M in MIL-PRF-38535, appendix A shall be provided with each lot of microcircuits delivered to this drawing.

3.8 Notification of change for device class M. For device class M, notification to DLA Land and Maritime-VA of change of product (see 6.2 herein) involving devices acquired to this drawing is required for any change that affects this drawing.

3.9 Verification and review for device class M. For device class M, DLA Land and Maritime, DLA Land and Maritime's agent, and the acquiring activity retain the option to review the manufacturer's facility and applicable required documentation. Offshore documentation shall be made available onshore at the option of the reviewer.

3.10 Microcircuit group assignment for device class M. Device class M devices covered by this drawing shall be in microcircuit group number 49 (see MIL-PRF-38535, appendix A).

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TABLE I. Electrical performance characteristics.

Test	Symbol	Conditions <u>1/</u> -55°C ≤ TA ≤ +125°C unless otherwise specified	Group A subgroups	Device type	Limits <u>2/</u>		Unit
					Min	Max	
Input bias current, noninverting	IBN		1,2	01	-22	+22	μA
			3		-44	+44	
Input bias current, average temperature coefficient, noninverting	DIBN	<u>3/</u>	2	01	-125	+125	nA/°C
			3		-275	+275	
Input bias current, inverting	IBI		1	01	-20	+20	μA
			2		-30	+30	
			3		-36	+36	
Input bias current, average temperature coefficient, inverting	DIBI	<u>3/</u>	2	01	-100	+100	nA/°C
			3		-200	+200	
Input offset voltage	VIO		1	01	-4.5	+4.5	mV
			2		-9.5	+9.5	
			3		-8.5	+8.5	
Input offset voltage, average temperature coefficient	DVIO	<u>3/</u>	2	01	-50	+50	μV/°C
Supply current, no load	ICC		1,2,3	01		14.2	mA
Power supply rejection ratio	PSRR	-VCC = -4.5 V to -5.0 V, +VCC = +4.5 V to +5.0 V	1,2,3	01	45		dB
Output current	+IO	<u>3/</u>	1,2	01	+50		mA
			3		+36		
	-IO		1,2			-50	
			3			-36	
Output voltage range	+VO	<u>3/</u>	1,2	01	+3.2		V
			3		+3.0		
	-VO		1,2			-3.2	
			3			-3.0	
Noninverting input resistance	RIN	<u>3/</u>	1	01	500		kΩ
			2		1000		
			3		250		
Noninverting input capacitance	CIN	<u>3/</u>	4,5,6	01		2	pF

See footnotes at end of table.

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TABLE I. Electrical performance characteristics - Continued.

Test	Symbol	Conditions <u>1/</u> -55°C ≤ TA ≤ +125°C unless otherwise specified	Group A subgroups	Device type	Limits <u>2/</u>		Unit
					Min	Max	
Output impedance	Ro	<u>3/</u>	1,2	01		0.2	Ω
			3			0.3	
Common mode rejection ratio	CMRR	VCM = ±1.0 V <u>3/</u>	4,5,6	01	45		dB
Small signal bandwidth	SSBW	-3 dB bandwidth <u>3/</u> VOUT < 2 VPP	4,6	01	250		MHz
			5		200		
Large signal bandwidth	LSBW	-3 db bandwidth <u>3/</u> VOUT < 5 VPP	4,6	01	90		MHz
			5		80		
Gain flatness peaking	GFPL	0.1 MHz to 75 MHz, VOUT < 0.5 VPP	4	01		0.4	dB
			5,6 <u>4/</u>			0.8	
	GFPH	> 75 MHz, VOUT < 0.5 VPP	4				
			5,6 <u>4/</u>				
Gain flatness rolloff	GFR1	0.1 MHz to 125 MHz	4	01		1.0	dB
			5,6 <u>4/</u>				
	GFR2	At 200 MHz	4		2.2		
			5 <u>4/</u>		3.0		
		6 <u>4/</u>	2.0				
Linear phase deviation	LPD	.01 MHz to 100 MHz <u>3/</u>	4,6	01		0.8	Degree
			5			1.0	
Differential gain	DG	RL = 150 Ω, <u>3/</u> 3.58 MHz, 4.43 MHz	4,5	01		.06	%
			6			.07	
Differential phase	DP	RL = 150 Ω, <u>3/</u> 3.58 MHz, 4.43 MHz	4,5,6	01		.02	Degree
2nd harmonic distortion	HD2	2 VPP at 20 MHz	4	01		-52	dBc
			5,6 <u>4/</u>				
	HD2L	2 VPP at 5 MHz <u>3/</u>	4,5		-81		
			6		-78		
	HD2H	2 VPP at 60 MHz <u>3/</u>	4,5		-44		
			6		-41		
3rd harmonic distortion	HD3	2 VPP at 20 MHz	4	01		-65	dBc
			5,6 <u>4/</u>				
	HD3L	2 VPP at 5 MHz <u>3/</u>	4,5,6		-76		
	HD3H	2 VPP at 60 MHz <u>3/</u>			-52		

See footnotes at end of table.

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TABLE I. Electrical performance characteristics - Continued.

Test	Symbol	Conditions <u>1/</u> -55°C ≤ TA ≤ +125°C unless otherwise specified	Group A subgroups	Device type	Limits <u>2/</u>		Unit
					Min	Max	
Rise and fall time	tRS	2 V step, CL < 10 pF, <u>3/</u> measured between 10% and 90% points	9,10,11	01		1.6	ns
	tRL	5 V step, CL < 10 pF, <u>3/</u> measured between 10% and 90% points	9,11			4.2	
			10			4.6	
Settling time	ts	CL < 10 pF, 2 V step <u>3/</u> at 0.1% of the final value	9,10,11	01		12	ns
Overshoot	OS	2 V step, CL < 10 pF <u>3/</u>	9,10	01		18	%
			11			15	
Slew rate	SR	VOUT = 4 V step, <u>3/</u> CL < 10 pF, measured at ±1 V	4,5,6	01	1000		V/μs
Equivalent input noise, noninverting voltage	VN	> 1 MHz <u>3/</u>	4,6	01		2.8	nV /
			5			3.1	√Hz
Equivalent input noise, inverting current	ICN	> 1 MHz <u>3/</u>	4,6	01		18	pA /
			5			20	√Hz
Equivalent input noise, noninverting current	NCN	> 1 MHz <u>3/</u>	4,6	01		4.0	pA /
			5			4.5	√Hz
Equivalent input noise, total noise floor	SNF	> 1 MHz <u>3/</u>	4,6	01		-155	dBm
			5			-154	1 Hz
Equivalent input noise, total integrated noise	INV	1 MHz to 150 MHz <u>3/</u>	4,6	01		47	μV
			5			52	

1/ Unless otherwise specified, RL = 100 Ω, VCC = ±5 V dc, AV = +2, feedback resistor (RF) = 250 Ω, gain resistor (RG) = 250 Ω.

2/ The algebraic convention, whereby the most negative value is a minimum and the most positive a maximum, is used in this table. Negative current shall be defined as conventional current flow out of a device terminal.

3/ Guaranteed, if not tested.

4/ This parameter is group A sample tested only and is excluded from final electrical testing, but is guaranteed to the limits specified.

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Device type	01	
Case outlines	P	2
Terminal number	Terminal symbol	
1	NC	NC
2	VINV	VNONINV
3	VNONINV	NC
4	-VCC	-VCC
5	NC	NC
6	VOUT	NC
7	+VCC	NC
8	NC	NC
9	---	NC
10	---	NC
11	---	NC
12	---	VOUT
13	---	NC
14	---	+VCC
15	---	NC
16	---	NC
17	---	NC
18	---	NC
19	---	NC
20	---	VINV

FIGURE 1. Terminal connections.

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4. VERIFICATION

4.1 Sampling and inspection. For device classes Q and V, sampling and inspection procedures shall be in accordance with MIL-PRF-38535 or as modified in the device manufacturer's Quality Management (QM) plan. The modification in the QM plan shall not affect the form, fit, or function as described herein. For device class M, sampling and inspection procedures shall be in accordance with MIL-PRF-38535, appendix A.

4.2 Screening. For device classes Q and V, screening shall be in accordance with MIL-PRF-38535, and shall be conducted on all devices prior to qualification and technology conformance inspection. For device class M, screening shall be in accordance with method 5004 of MIL-STD-883, and shall be conducted on all devices prior to quality conformance inspection.

4.2.1 Additional criteria for device class M.

- a. Burn-in test, method 1015 of MIL-STD-883.
  - (1) Test condition B. The test circuit shall be maintained by the manufacturer under document revision level control and shall be made available to the preparing or acquiring activity upon request. The test circuit shall specify the inputs, outputs, biases, and power dissipation, as applicable, in accordance with the intent specified in method 1015 of MIL-STD-883.
  - (2) T<sub>A</sub> = +125°C, minimum.
- b. Interim and final electrical test parameters shall be as specified in table II herein.

4.2.2 Additional criteria for device classes Q and V.

- a. The burn-in test duration, test condition and test temperature, or approved alternatives shall be as specified in the device manufacturer's QM plan in accordance with MIL-PRF-38535. The burn-in test circuit shall be maintained under document revision level control of the device manufacturer's Technology Review Board (TRB) in accordance with MIL-PRF-38535 and shall be made available to the acquiring or preparing activity upon request. The test circuit shall specify the inputs, outputs, biases, and power dissipation, as applicable, in accordance with the intent specified in method 1015 of MIL-STD-883.
- b. Interim and final electrical test parameters shall be as specified in table II herein.
- c. Additional screening for device class V beyond the requirements of device class Q shall be as specified in MIL-PRF-38535, appendix B.

4.3 Qualification inspection for device classes Q and V. Qualification inspection for device classes Q and V shall be in accordance with MIL-PRF-38535. Inspections to be performed shall be those specified in MIL-PRF-38535 and herein for groups A, B, C, D, and E inspections (see 4.4.1 through 4.4.4).

4.4 Conformance inspection. Technology conformance inspection for classes Q and V shall be in accordance with MIL-PRF-38535 including groups A, B, C, D, and E inspections, and as specified herein. Quality conformance inspection for device class M shall be in accordance with MIL-PRF-38535, appendix A and as specified herein. Inspections to be performed for device class M shall be those specified in method 5005 of MIL-STD-883 and herein for groups A, B, C, D, and E inspections (see 4.4.1 through 4.4.4).

4.4.1 Group A inspection.

- a. Tests shall be as specified in table II herein.
- b. Subgroups 7 and 8 in table I, method 5005 of MIL-STD-883 shall be omitted.

4.4.2 Group C inspection. The group C inspection end-point electrical parameters shall be as specified in table II herein.

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TABLE II. Electrical test requirements.

Test requirements	Subgroups (in accordance with MIL-STD-883, method 5005, table I)	Subgroups (in accordance with MIL-PRF-38535, table III)	
	Device class M	Device class Q	Device class V
Interim electrical parameters (see 4.2)	---	---	---
Final electrical parameters (see 4.2)	1,2,3,4 <u>1/</u>	1,2,3,4 <u>1/</u>	1,2,3,4 <u>1/</u>
Group A test requirements (see 4.4)	1,2,3,4,5, <u>2/</u> 6,9,10,11	1,2,3,4,5, <u>2/</u> 6,9,10,11	1,2,3,4,5, <u>2/</u> 6,9,10,11
Group C end-point electrical parameters (see 4.4)	1	1	1,2,3,4,5,6
Group D end-point electrical parameters (see 4.4)	1	1	1
Group E end-point electrical parameters (see 4.4)	---	---	---

1/ PDA applies to subgroup 1.

2/ Subgroups 9, 10, and 11 shall be guaranteed, if not tested, to the limits specified in table I.

4.4.2.1 Additional criteria for device class M. Steady-state life test conditions, method 1005 of MIL-STD-883:

- a. Test condition B. The test circuit shall be maintained by the manufacturer under document revision level control and shall be made available to the preparing or acquiring activity upon request. The test circuit shall specify the inputs, outputs, biases, and power dissipation, as applicable, in accordance with the intent specified in method 1005 of MIL-STD-883.
- b.  $T_A = +125^\circ\text{C}$ , minimum.
- c. Test duration: 1,000 hours, except as permitted by method 1005 of MIL-STD-883.

4.4.2.2 Additional criteria for device classes Q and V. The steady-state life test duration, test condition and test temperature, or approved alternatives shall be as specified in the device manufacturer's QM plan in accordance with MIL-PRF-38535. The test circuit shall be maintained under document revision level control by the device manufacturer's TRB in accordance with MIL-PRF-38535 and shall be made available to the acquiring or preparing activity upon request. The test circuit shall specify the inputs, outputs, biases, and power dissipation, as applicable, in accordance with the intent specified in method 1005 of MIL-STD-883.

4.4.3 Group D inspection. The group D inspection end-point electrical parameters shall be as specified in table II herein.

4.4.4 Group E inspection. Group E inspection is required only for parts intended to be marked as radiation hardness assured (see 3.5 herein).

- a. End-point electrical parameters shall be as specified in table II herein.
- b. For device classes Q and V, the devices or test vehicle shall be subjected to radiation hardness assured tests as specified in MIL-PRF-38535 for the RHA level being tested. For device class M, the devices shall be subjected to radiation hardness assured tests as specified in MIL-PRF-38535, appendix A for the RHA level being tested. All device classes must meet the postirradiation end-point electrical parameter limits as defined in table I at  $T_A = +25^\circ\text{C} \pm 5^\circ\text{C}$ , after exposure, to the subgroups specified in table II herein.

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5. PACKAGING

5.1 Packaging requirements. The requirements for packaging shall be in accordance with MIL-PRF-38535 for device classes Q and V or MIL-PRF-38535, appendix A for device class M.

6. NOTES

6.1 Intended use. Microcircuits conforming to this drawing are intended for use for Government microcircuit applications (original equipment), design applications, and logistics purposes.

6.1.1 Replaceability. Microcircuits covered by this drawing will replace the same generic device covered by a contractor prepared specification or drawing.

6.1.2 Substitutability. Device class Q devices will replace device class M devices.

6.2 Configuration control of SMD's. All proposed changes to existing SMD's will be coordinated with the users of record for the individual documents. This coordination will be accomplished using DD Form 1692, Engineering Change Proposal.

6.3 Record of users. Military and industrial users should inform DLA Land and Maritime when a system application requires configuration control and which SMD's are applicable to that system. DLA Land and Maritime will maintain a record of users and this list will be used for coordination and distribution of changes to the drawings. Users of drawings covering microelectronic devices (FSC 5962) should contact DLA Land and Maritime-VA, telephone (614) 692-8108.

6.4 Comments. Comments on this drawing should be directed to DLA Land and Maritime-VA, Columbus, Ohio 43218-3990, or telephone (614) 692-0540.

6.5 Abbreviations, symbols, and definitions. The abbreviations, symbols, and definitions used herein are defined in MIL-PRF-38535 and MIL-HDBK-1331.

6.6 Sources of supply.

6.6.1 Sources of supply for device classes Q and V. Sources of supply for device classes Q and V are listed in MIL-HDBK-103 and QML-38535. The vendors listed in MIL-HDBK-103 and QML-38535 have submitted a certificate of compliance (see 3.6 herein) to DLA Land and Maritime-VA and have agreed to this drawing.

6.6.2 Approved sources of supply for device class M. Approved sources of supply for class M are listed in MIL-HDBK-103. The vendors listed in MIL-HDBK-103 have agreed to this drawing and a certificate of compliance (see 3.6 herein) has been submitted to and accepted by DLA Land and Maritime-VA.

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DATE: 18-09-25

Approved sources of supply for SMD 5962-92034 are listed below for immediate acquisition information only and shall be added to MIL-HDBK-103 and QML-38535 during the next revision. MIL-HDBK-103 and QML-38535 will be revised to include the addition or deletion of sources. The vendors listed below have agreed to this drawing and a certificate of compliance has been submitted to and accepted by DLA Land and Maritime-VA. This information bulletin is superseded by the next dated revision of MIL-HDBK-103 and QML-38535. DLA Land and Maritime maintains an online database of all current sources of supply at <https://landandmaritimeapps.dla.mil/programs/smcr/>.

Standard microcircuit drawing PIN <u>1/</u>	Vendor CAGE number	Vendor similar PIN <u>2/</u>
5962-9203401MPA	3V146	CLC409A/BPA
	<u>3/</u>	CLC409AJ-QML
5962-9203401M2A	3V146	CLC409A/B2A
	<u>3/</u>	CLC409AE-QML

- 1/ The lead finish shown for each PIN representing a hermetic package is the most readily available from the manufacturer listed for that part. If the desired lead finish is not listed contact the vendor to determine its availability.
- 2/ Caution. Do not use this number for item acquisition. Items acquired to this number may not satisfy the performance requirements of this drawing.
- 3/ Not available from an approved source of supply.

Vendor CAGE number

3V146

Vendor name and address

Rochester Electronics Inc.  
16 Malcolm Hoyt Drive  
Newburyport, MA 01950

The information contained herein is disseminated for convenience only and the Government assumes no liability whatsoever for any inaccuracies in the information bulletin.